

## PACKAGING PROCESS OF ELECTRONIC COMPONENT

### ABSTRACT OF THE DISCLOSURE

A packaging process of an electronic component includes the following steps. Firstly, a semi-package unit is provided. The semi-package unit includes a first insulation layer and an electronic component. The electronic component is partially embedded within the first insulation layer. The electronic component includes at least one conducting terminal. Then, a metal layer is formed over the surface of the semi-package unit and a part of the metal layer is removed, so that a metal mask is formed on the surface of the semi-package unit and the at least one conducting terminals is exposed. Then, a metal re-distribution layer is formed on the metal mask and the at least one conducting terminal. Then, a part of the metal re-distribution layer and a part of the metal mask are removed, so that at least one contact pad corresponding to the at least one conducting terminal is produced.

[ Figure 1M ]